

HMW60N075F7

N-Channel eMOS F7 Power MOSFET

600 V, 42 A, 75 mΩ

Description

The 600V eMOS F7 is a fast recovery type MOSFET using E7 technology. eMOS F7 is an advanced Power Master Semiconductor's Super Junction MOSFET family by utilizing charge balance technology for excellent low on-resistance and gate charge. It combines the benefits of a fast switching performance with ease of usage and robustness. Additionally, we offer low reverse recovery time(t_{rr}) and reverse recovery charge(Q_{rr}). Thus, 600V eMOS F7 is very suitable for the bridge structure topology, especially for resonant converters (LLC, PSFB, etc.).

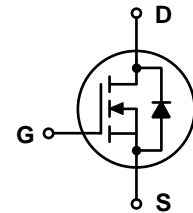
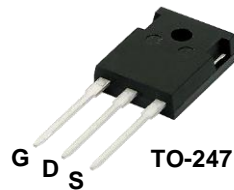
Applications

- Soft Switching Topologies
- Telecom and Server Power Supplies
- EV Charger and Industrial Power Supplies

Features

$BV_{DSS} @ T_{J,max}$	I_D	$R_{DS(on),max}$	$Q_{g,typ}$
650 V	42 A	75 mΩ	80 nC

- Reduced Switching & Conduction Losses
- Fast Recovery Body-Diode
- Lower Gate Resistance
- 100% Avalanche Tested
- Pb-free and RoHS Compliant



Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	600	V
V_{GSS}	Gate to Source Voltage	± 30	V
I_D	Drain Current	Continuous ($T_C = 25^\circ\text{C}$)	42
		Continuous ($T_C = 100^\circ\text{C}$)	26.6
I_{DM}	Drain Current	Pulsed (Note1)	126
E_{AS}	Single Pulsed Avalanche Energy	(Note2)	254
I_{AS}	Avalanche Current	(Note2)	6.3
E_{AR}	Repetitive Avalanche Energy	(Note1)	3.29
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt	(Note3)	
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	329
		Derate Above 25°C	2.63
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds	260	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.38	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
HMW60N075F7	HMW60N075F7	TO-247	Tube	30 units

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
--------	-----------	-----------------	-----	-----	-----	------

Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	600			V
		$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 150^\circ\text{C}$	650			
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$			10	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$		75		
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$			± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.8\text{ mA}$	3.0		5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 21.5\text{ A}$		64	75	m Ω

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V},$ $f = 250\text{ kHz}$		3044		pF
C_{oss}	Output Capacitance			79		pF
$C_{o(tr)}$	Time Related Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$		817		pF
$C_{o(er)}$	Energy Related Output Capacitance			124		pF
$Q_{g(tot)}$	Total Gate Charge at 10 V	$V_{DS} = 400\text{ V}, I_D = 21.5\text{ A},$ $V_{GS} = 10\text{ V}$		80		nC
Q_{gs}	Gate to Source Charge			19		nC
Q_{gd}	Gate to Drain "Miller" Charge			39		nC
R_G	Gate Resistance	$f = 1\text{ MHz}$		1		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 400\text{ V}, I_D = 21.5\text{ A},$ $V_{GS} = 10\text{ V}, R_G = 4.7\text{ }\Omega$ See Figure 13		22		ns
t_r	Turn-On Rise Time			11		ns
$t_{d(off)}$	Turn-Off Delay Time			67		ns
t_f	Turn-Off Fall Time			8		ns

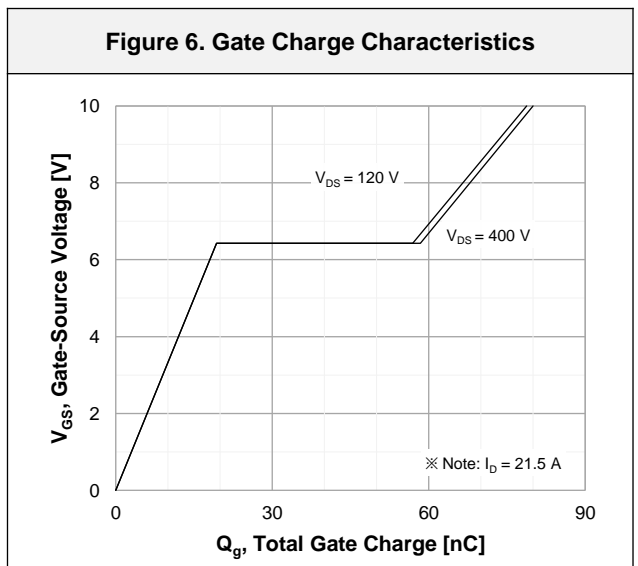
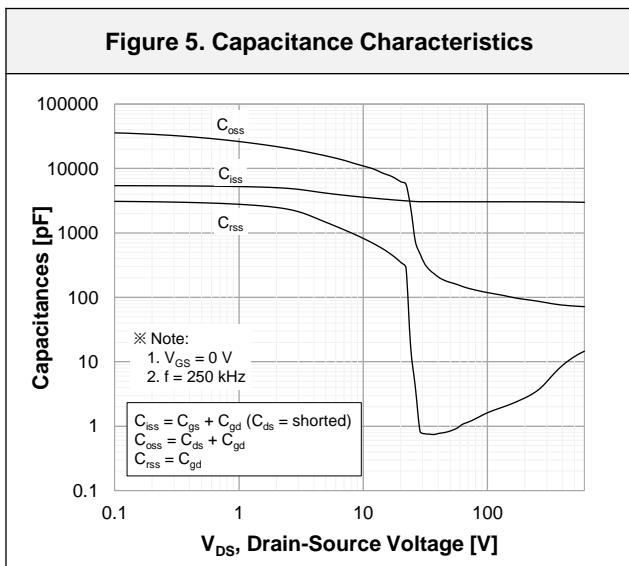
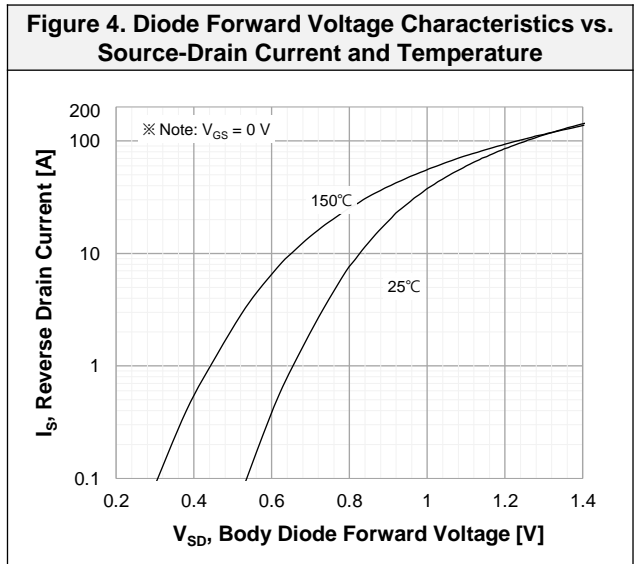
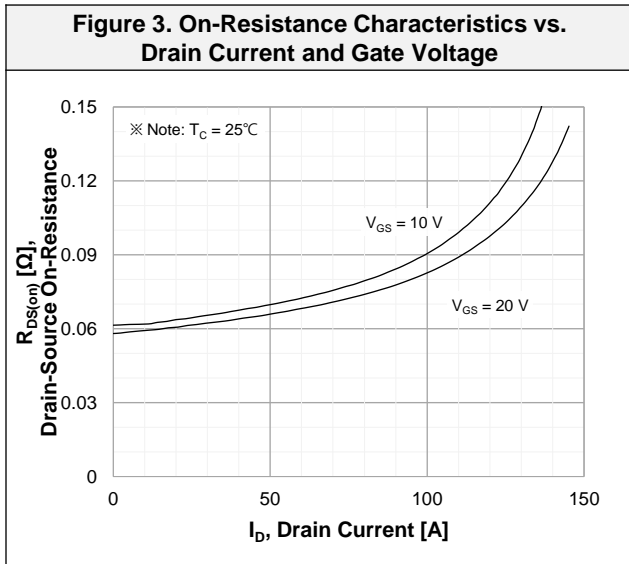
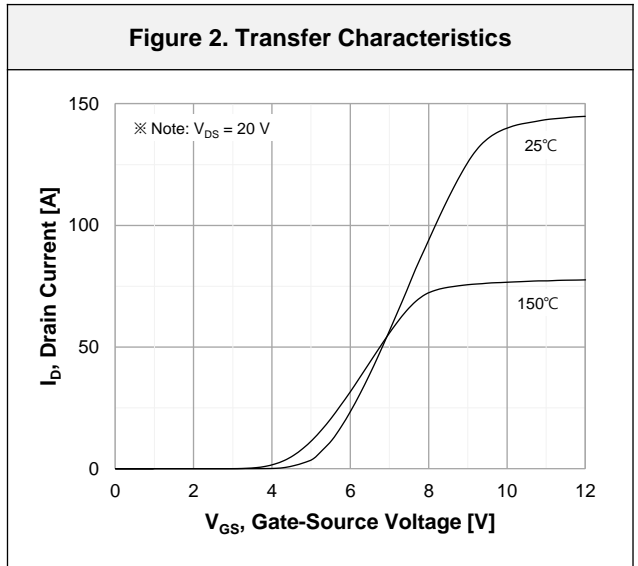
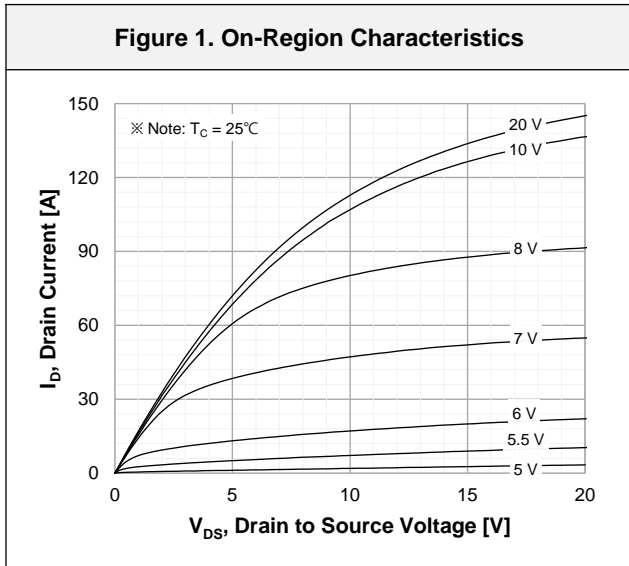
Source-Drain Diode Characteristics

I_S	Maximum Continuous Diode Forward Current			42		A
I_{SM}	Maximum Pulsed Diode Forward Current			126		A
V_{SD}	Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 21.5\text{ A}$			1.2	V
t_{rr}	Reverse Recovery Time	$V_{DD} = 400\text{ V}, I_{SD} = 21.5\text{ A},$ $di_F/dt = 100\text{ A}/\mu\text{s}$		176		ns
Q_{rr}	Reverse Recovery Charge			1.54		μC

※Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. $I_{AS} = 6.3\text{ A}, R_G = 25\text{ }\Omega$, starting $T_J = 25^\circ\text{C}$.
3. $I_{SD} \leq 21.5\text{ A}, di/dt \leq 100\text{ A}/\mu\text{s}, V_{DD} \leq 400\text{ V}$, starting $T_J = 25^\circ\text{C}$.

Typical Performance Characteristics



Typical Performance Characteristics

Figure 7. Breakdown Voltage Characteristics vs. Temperature

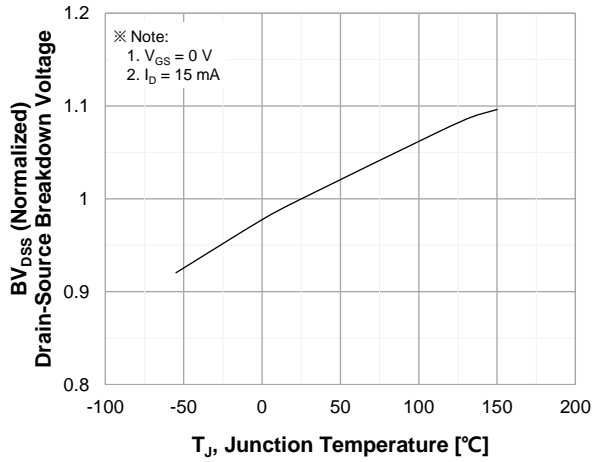


Figure 8. On-Resistance Characteristics vs. Temperature

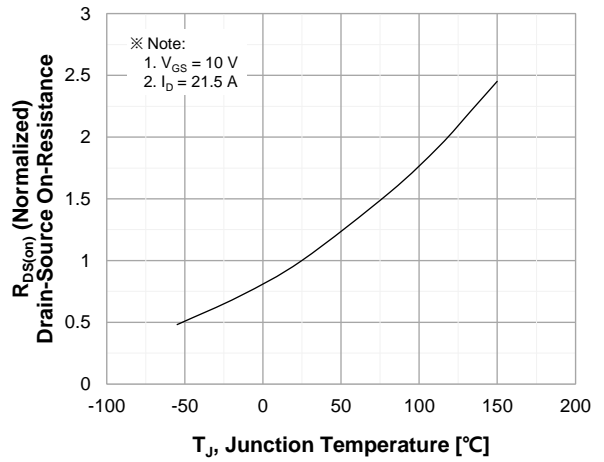


Figure 9. Maximum Safe Operating Area

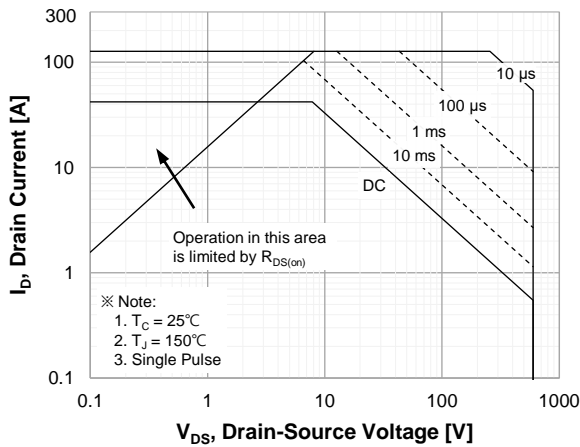


Figure 10. Maximum Drain Current vs. Case Temperature

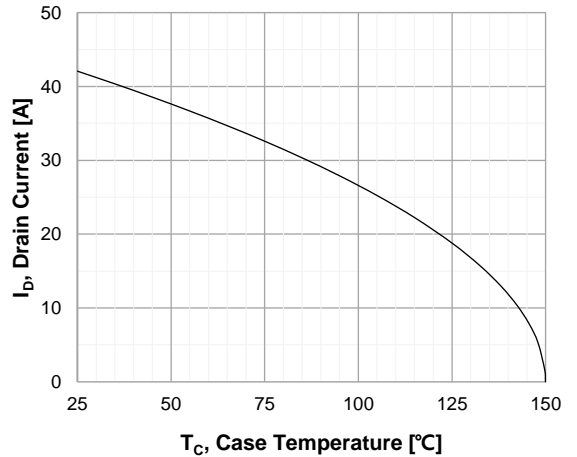


Figure 11. E_oss vs. Drain to Source Voltage

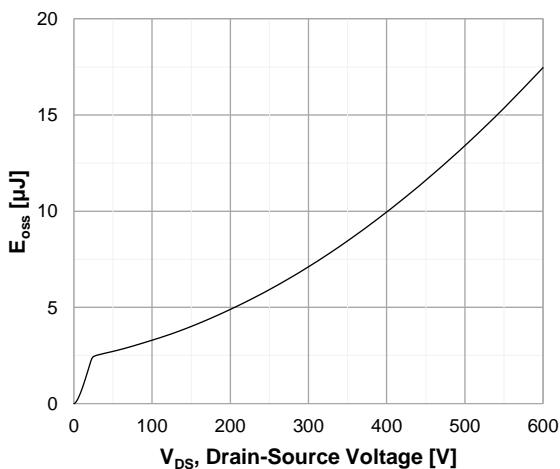
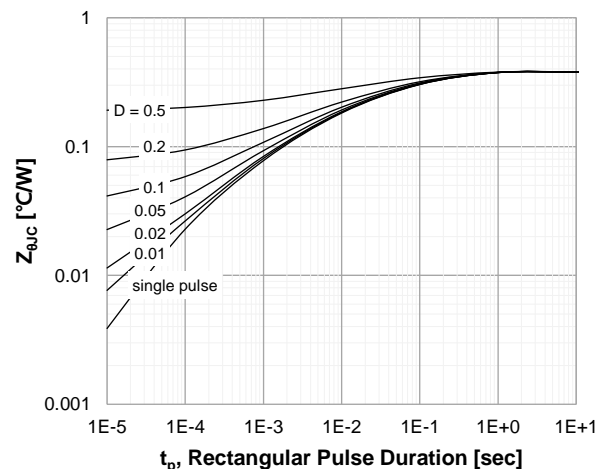


Figure 12. Transient Thermal Response Curve



Test Circuits

Figure 13. Inductive Load Switching Test Circuit and Waveforms

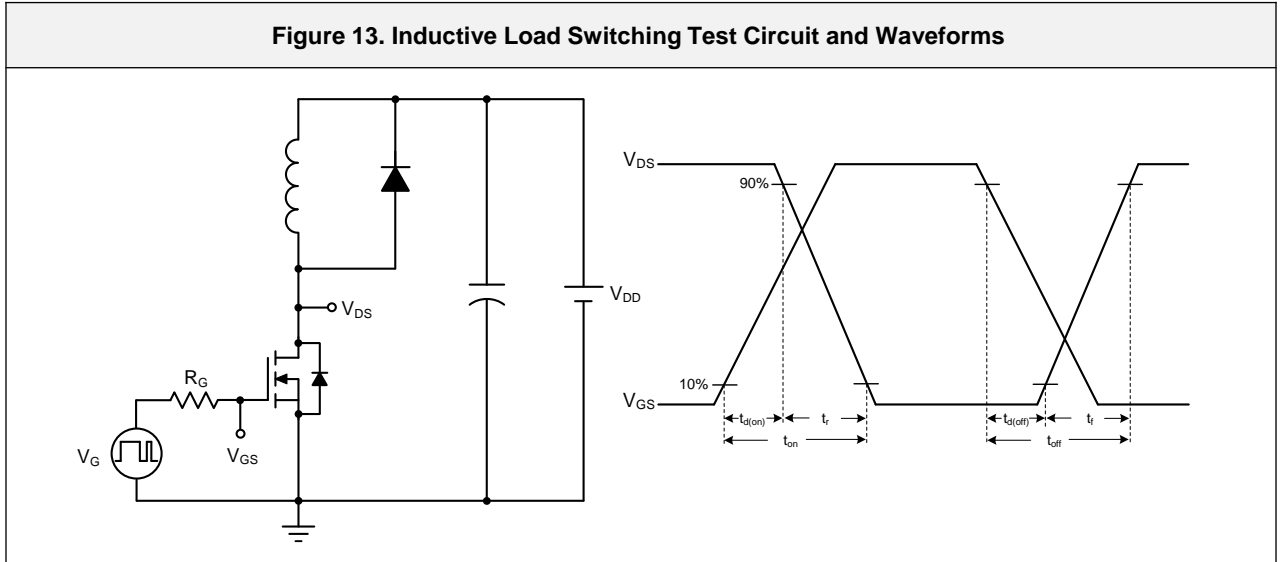


Figure 14. Unclamped Inductive Switching Test Circuit and Waveforms

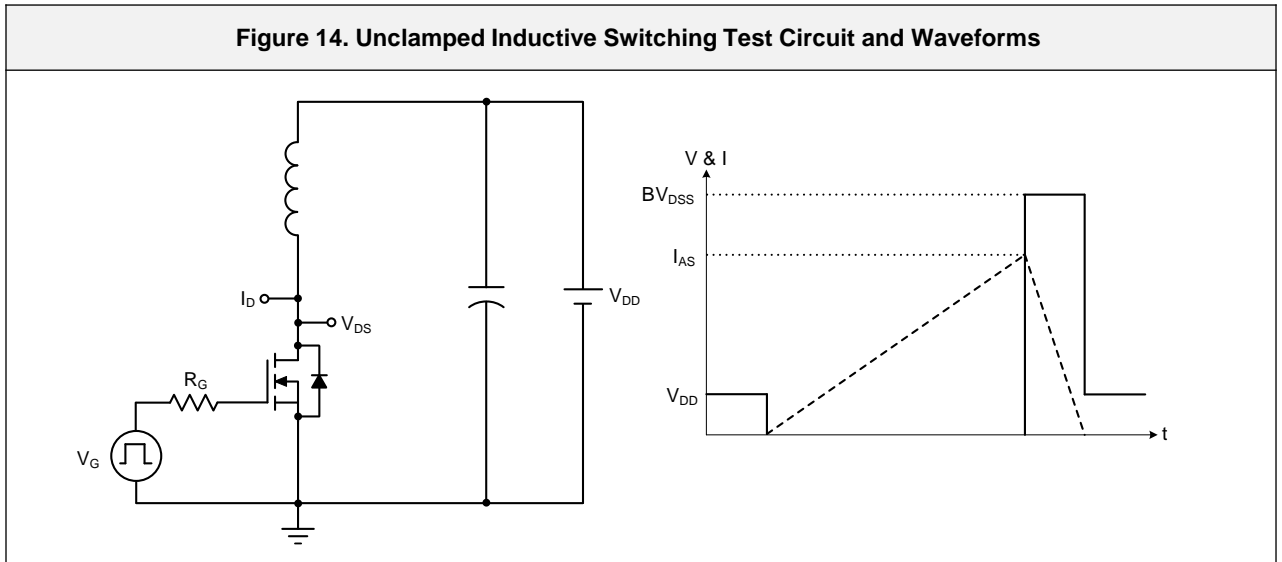
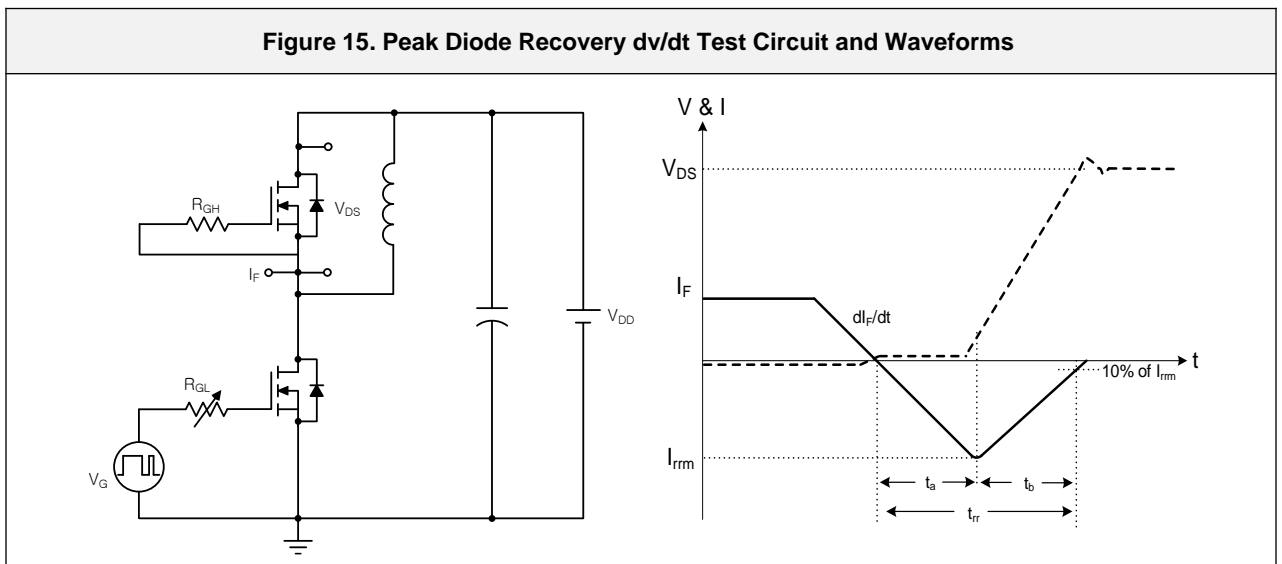
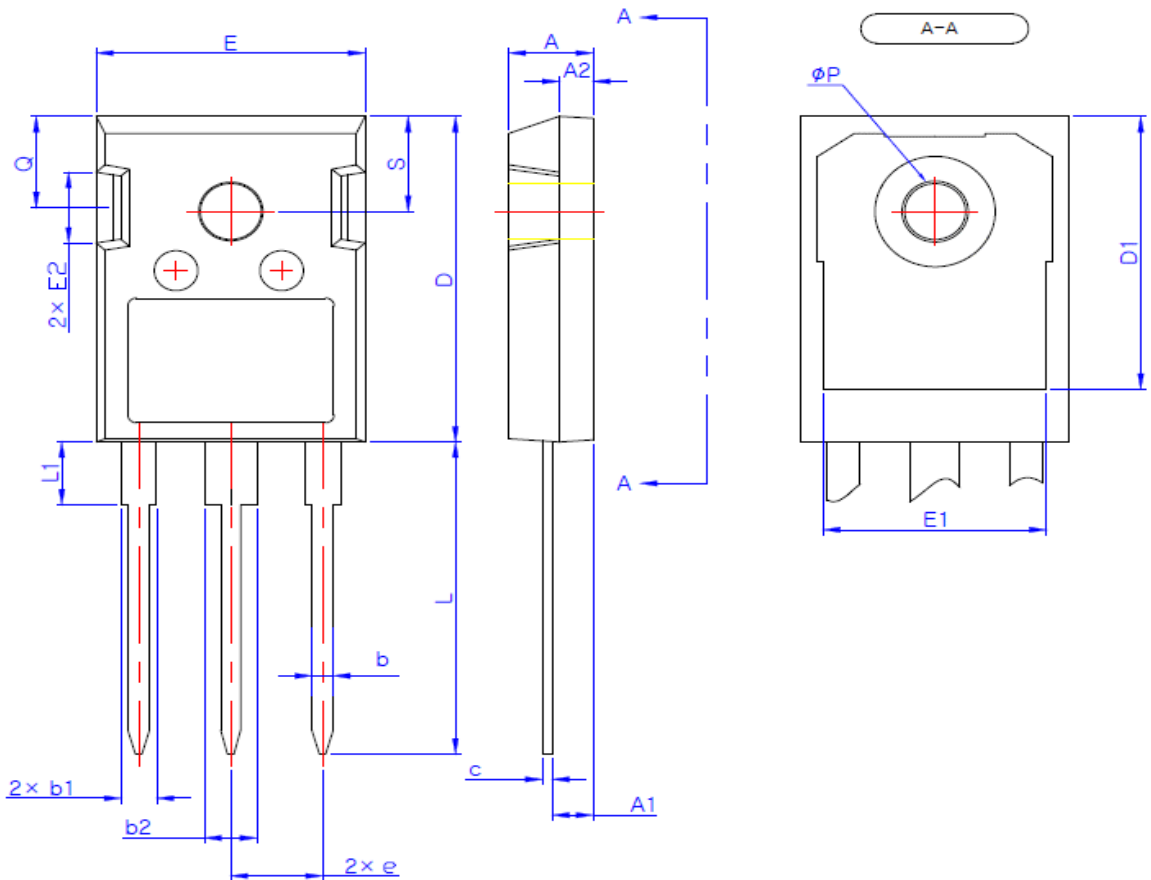


Figure 15. Peak Diode Recovery dv/dt Test Circuit and Waveforms



Package Outlines

TO-247



SYMBOL	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.91	2.06	2.20
b2	2.92	3.06	3.20
c	0.50	0.60	0.70
D	20.80	21.07	21.34
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.06	13.26	13.46
E2	4.32	4.58	4.83
e	5.45 BSC		
L	19.85	20.05	20.25
L1	4.05	4.27	4.49
φP	3.55	3.60	3.65
Q	5.59	5.89	6.19
S	6.15 BSC		

* Dimensions in millimeters